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Applications of "Embedded - Microcontrollers"

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	13
Program Memory Size	896B (512 x 14)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	80 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 5.5V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	20-SSOP (0.209", 5.30mm Width)
Supplier Device Package	20-SSOP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lc554t-04i-ss

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TABLE 1-1: PIC16C55X FAMILY OF DEVICES

		PIC16C554	PIC16C557	PIC16C558
Clock	Maximum Frequency of Operation (MHz)	20	20	20
Memory	EPROM Program Memory (x14 words)	512	2K	2K
	Data Memory (bytes)	80	128	128
Peripherals	Timer Module(s)	TMR0	TMR0	TMR0
Features	Interrupt Sources	3	3	3
	I/O Pins	13	22	13
	Voltage Range (Volts)	2.5-5.5	2.5-5.5	2.5-5.5
	Brown-out Reset	—	—	—
	Packages	18-pin DIP, SOIC; 20-pin SSOP	28-pin DIP, SOIC; 28-pin SSOP	18-pin DIP, SOIC, SSOP
All PIC® Family devices have Power-on Reset, selectable Watchdog Timer, selectable code protect and high I/O current capability. All PIC16C55X Family devices use serial programming with clock pin RB6 and data pin RB7.				

TABLE 3-1: PIC16C55X PINOUT DESCRIPTION

Name	Pin Number			Pin Type	Buffer Type	Description
	PDIP	SOIC	SSOP			
OSC1/CLKIN	16	16	18	I	ST/CMOS	Oscillator crystal input/external clock source output.
OSC2/CLKOUT	15	15	17	O	—	Oscillator crystal output. Connects to crystal or resonator in Crystal Oscillator mode. In RC mode, OSC2 pin outputs CLKOUT which has 1/4 the frequency of OSC1, and denotes the instruction cycle rate.
$\overline{MCLR}$/VPP	4	4	4	I/P	ST	Master clear (Reset) input/programming voltage input. This pin is an active low RESET to the device.
RA0	17	17	19	I/O	ST	Bi-directional I/O port
RA1	18	18	20	I/O	ST	Bi-directional I/O port
RA2	1	1	1	I/O	ST	Bi-directional I/O port
RA3	2	2	2	I/O	ST	Bi-directional I/O port
RA4/T0CKI	3	3	3	I/O	ST	Bi-directional I/O port or external clock input for TMR0. Output is open drain type.
RB0/INT	6	6	7	I/O	TTL/ST(1)	Bi-directional I/O port can be software programmed for internal weak pull-up. RB0/INT can also be selected as an external interrupt pin.
RB1	7	7	8	I/O	TTL	Bi-directional I/O port can be software programmed for internal weak pull-up.
RB2	8	8	9	I/O	TTL	Bi-directional I/O port can be software programmed for internal weak pull-up.
RB3	9	9	10	I/O	TTL	Bi-directional I/O port can be software programmed for internal weak pull-up.
RB4	10	10	11	I/O	TTL	Bi-directional I/O port can be software programmed for internal weak pull-up. Interrupt-on-change pin.
RB5	11	11	12	I/O	TTL	Bi-directional I/O port can be software programmed for internal weak pull-up. Interrupt-on-change pin.
RB6	12	12	13	I/O	TTL/ST(2)	Bi-directional I/O port can be software programmed for internal weak pull-up. Interrupt-on-change pin. Serial programming clock.
RB7	13	13	14	I/O	TTL/ST(2)	Bi-directional I/O port can be software programmed for internal weak pull-up. Interrupt-on-change pin. Serial programming data.
RC0(3)	18	18	18	I/O	TTL	Bi-directional I/O port input buffer.
RC1(3)	19	19	19	I/O	TTL	Bi-directional I/O port input buffer.
RC2(3)	20	20	20	I/O	TTL	Bi-directional I/O port input buffer.
RC3(3)	21	21	21	I/O	TTL	Bi-directional I/O port input buffer.
RC4(3)	22	22	22	I/O	TTL	Bi-directional I/O port input buffer.
RC5(3)	23	23	23	I/O	TTL	Bi-directional I/O port input buffer.
RC6(3)	24	24	24	I/O	TTL	Bi-directional I/O port input buffer.
RC7(3)	25	25	25	I/O	TTL	Bi-directional I/O port input buffer.
VSS	5	5	5,6	P	—	Ground reference for logic and I/O pins.
VDD	14	14	15,16	P	—	Positive supply for logic and I/O pins.

Legend: O = Output, I/O = Input/output, P = Power, — = Not used, I = Input, ST = Schmitt Trigger input, TTL = TTL input

Note 1: This buffer is a Schmitt Trigger input when configured as the external interrupt.
2: This buffer is a Schmitt Trigger input when used in Serial Programming mode.
3: PIC16C557 only.

4.0 MEMORY ORGANIZATION

4.1 Program Memory Organization

The PIC16C55X has a 13-bit program counter capable of addressing an 8 K x 14 program memory space. Only the first 512 x 14 (0000h - 01FFh) for the PIC16C554 and 2K x 14 (0000h - 07FFh) for the PIC16C557 and PIC16C558 are physically implemented. Accessing a location above these boundaries will cause a wrap-around within the first 512 x 14 spaces in the PIC16C554, or 2K x 14 space of the PIC16C558 and PIC16C557. The RESET vector is at 0000h and the interrupt vector is at 0004h (Figure 4-1, Figure 4-2).

FIGURE 4-1: PROGRAM MEMORY MAP AND STACK FOR THE PIC16C554

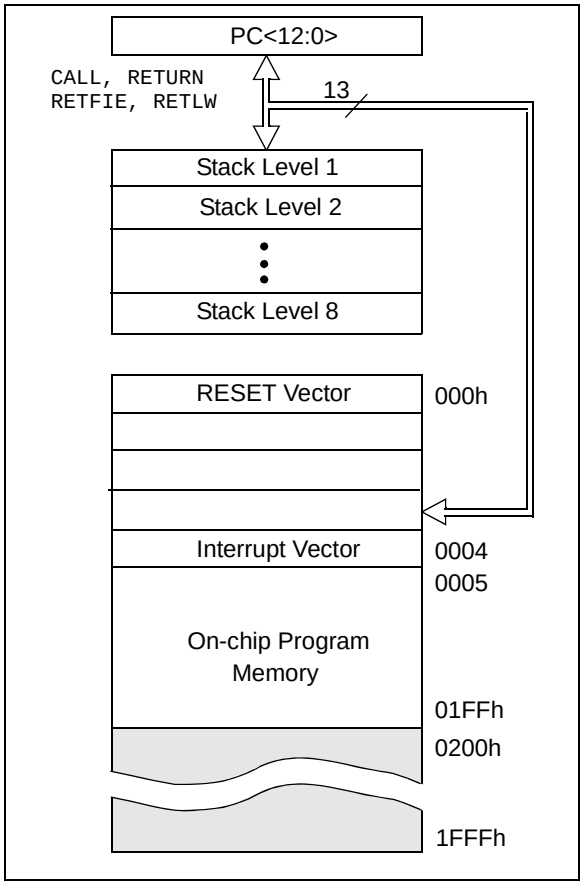
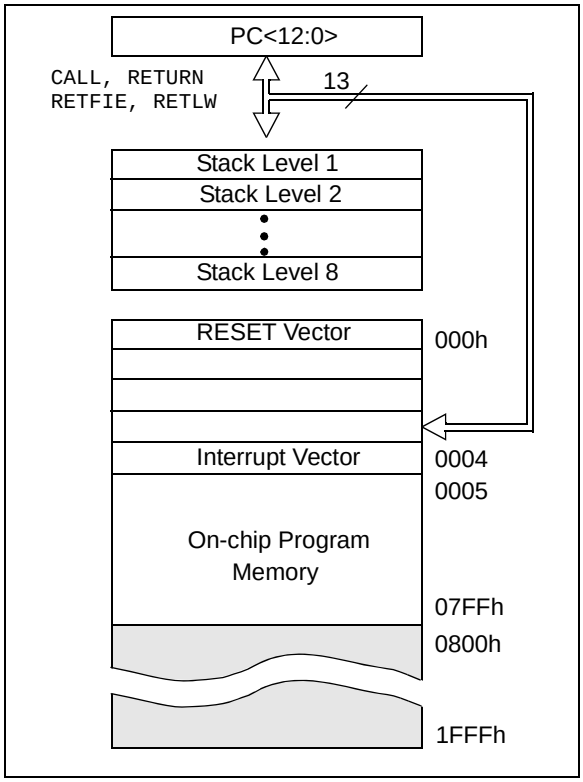


FIGURE 4-2: PROGRAM MEMORY MAP AND STACK FOR THE PIC16C557 AND PIC16C558



4.2 Data Memory Organization

The data memory (Figure 4-3 through Figure 4-5) is partitioned into two banks which contain the General Purpose Registers (GPR) and the Special Function Registers (SFR). Bank 0 is selected when the RP0 bit (STATUS <5>) is cleared. Bank 1 is selected when the RP0 bit is set. The Special Function Registers are located in the first 32 locations of each Bank. Register locations 20-6Fh (Bank 0) on the PIC16C554 and 20-7Fh (Bank 0) and A0-BFh (Bank 1) on the PIC16C558 and PIC16C557 are General Purpose Registers implemented as static RAM. Some special purpose registers are mapped in Bank 1.

4.2.1 GENERAL PURPOSE REGISTER FILE

The register file is organized as 80 x 8 in the PIC16C554 and 128 x 8 in the PIC16C557 and PIC16C558. Each can be accessed either directly or indirectly through the File Select Register, FSR (Section 4.4).

FIGURE 4-3: DATA MEMORY MAP FOR THE PIC16C554

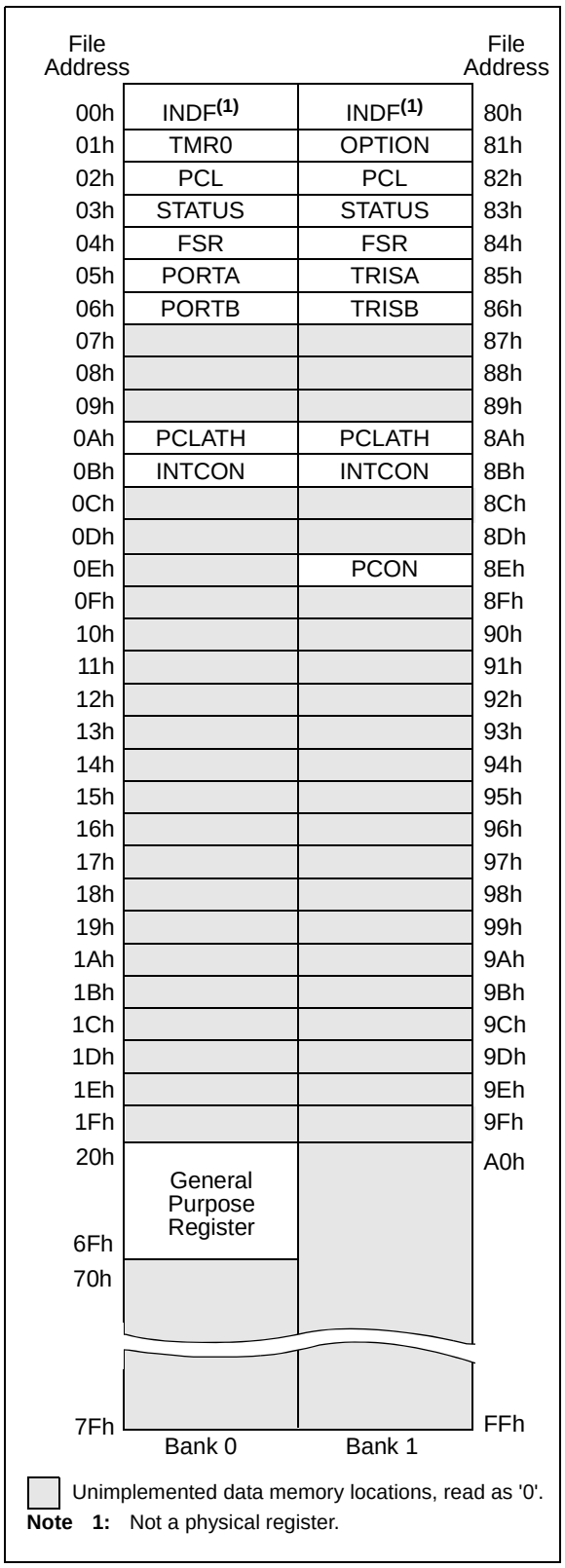
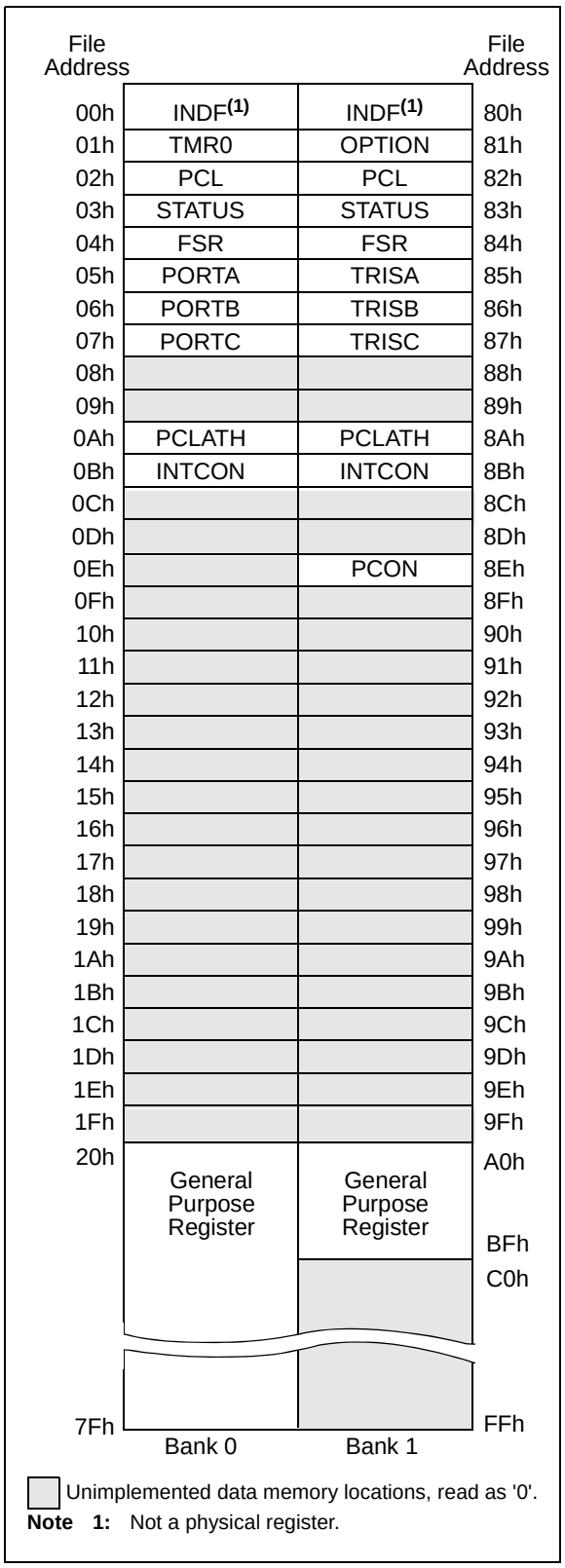


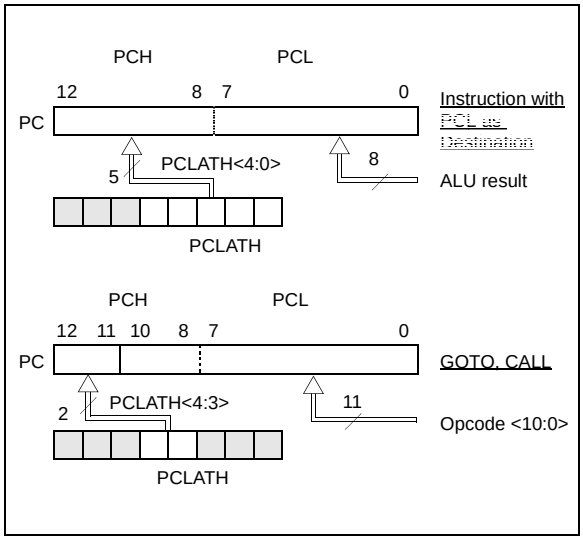
FIGURE 4-4: DATA MEMORY MAP FOR THE PIC16C557



4.3 PCL and PCLATH

The program counter (PC) is 13-bits wide. The low byte comes from the PCL register, which is a readable and writable register. The high bits (PC<12:8>) are not directly readable or writable and come from PCLATH. On any RESET, the PC is cleared. Figure 4-6 shows the two situations for the loading of the PC. The upper example in the figure shows how the PC is loaded on a write to PCL (PCLATH<4:0> → PCH). The lower example in Figure 4-6 shows how the PC is loaded during a CALL or GOTO instruction (PCLATH<4:3> → PCH).

FIGURE 4-6: LOADING OF PC IN DIFFERENT SITUATIONS



4.3.1 COMPUTED GOTO

A computed GOTO is accomplished by adding an offset to the program counter (ADDWF PCL). When doing a table read using a computed GOTO method, care should be exercised if the table location crosses a PCL memory boundary (each 256 byte block). Refer to the application note *"Implementing a Table Read"* (AN556).

4.3.2 STACK

The PIC16C55X family has an 8-level deep x 13-bit wide hardware stack (Figure 4-1 and Figure 4-2). The stack space is not part of either program or data space and the stack pointer is not readable or writable. The PC is PUSHed onto the stack when a CALL instruction is executed or an interrupt causes a branch. The stack is POPed in the event of a RETURN, RETLW or a RETFIE instruction execution. PCLATH is not affected by a PUSH or POP operation.

The stack operates as a circular buffer. This means that after the stack has been PUSHed eight times, the ninth push overwrites the value that was stored from the first push. The tenth push overwrites the second push (and so on).

Note 1: There are no status bits to indicate stack overflow or stack underflow conditions.

2: There are no instructions mnemonics called PUSH or POP. These are actions that occur from the execution of the CALL, RETURN, RETLW and RETFIE instructions, or vectoring to an interrupt address.

4.4 Indirect Addressing, INDF and FSR Registers

The INDF register is not a physical register. Addressing the INDF register will cause indirect addressing.

Indirect addressing is possible by using the INDF register. Any instruction using the INDF register actually accesses data pointed to by the file select register (FSR). Reading INDF itself indirectly will produce 00h. Writing to the INDF register indirectly results in a no-operation (although status bits may be affected). An effective 9-bit address is obtained by concatenating the 8-bit FSR register and the IRP bit (STATUS<7>), as shown in Figure 4-7. However, IRP is not used in the PIC16C55X.

A simple program to clear RAM locations 20h-2Fh using indirect addressing is shown in Example 4-1.

EXAMPLE 4-1: INDIRECT ADDRESSING

```
        movlw   0x20    ;initialize pointer
        movwf   FSR     ;to RAM
NEXT    clrf    INDF    ;clear INDF register
        incf    FSR     ;inc pointer
        btfss   FSR,4   ;all done?
        goto    NEXT    ;no clear next
                        ;yes continue
CONTINUE:
```

5.0 I/O PORTS

The PIC16C554 and PIC16C558 have two ports, PORTA and PORTB. The PIC16C557 has three ports, PORTA, PORTB and PORTC.

5.1 PORTA and TRISA Registers

PORTA is a 5-bit wide latch. RA4 is a Schmitt Trigger input and an open-drain output. Port RA4 is multiplexed with the T0CKI clock input. All other RA port pins have Schmitt Trigger input levels and full CMOS output drivers. All pins have data direction bits (TRIS registers) which can configure these pins as input or output.

A '1' in the TRISA register puts the corresponding output driver in a Hi-impedance mode. A '0' in the TRISA register puts the contents of the output latch on the selected pin(s).

Reading the PORTA register reads the status of the pins, whereas writing to it will write to the port latch. All write operations are read-modify-write operations. So a write to a port implies that the port pins are first read, then this value is modified and written to the port data latch.

Note 1: On RESET, the TRISA register is set to all inputs.

FIGURE 5-1: BLOCK DIAGRAM OF PORT PINS RA<3:0>

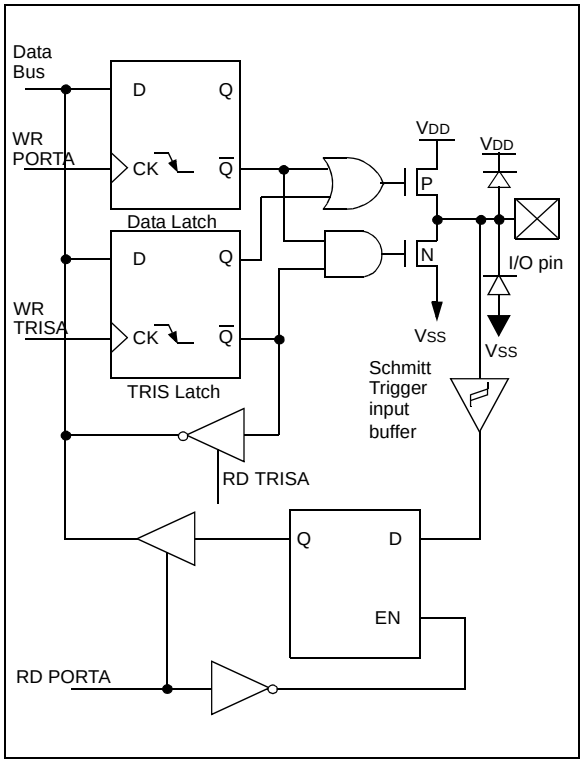
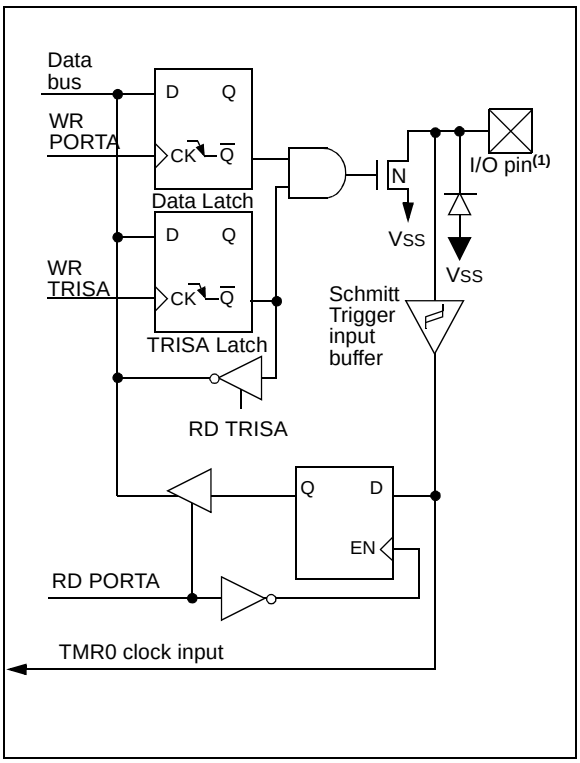


FIGURE 5-2: BLOCK DIAGRAM OF RA4 PIN



6.3 RESET

The PIC16C55X differentiates between various kinds of RESET:

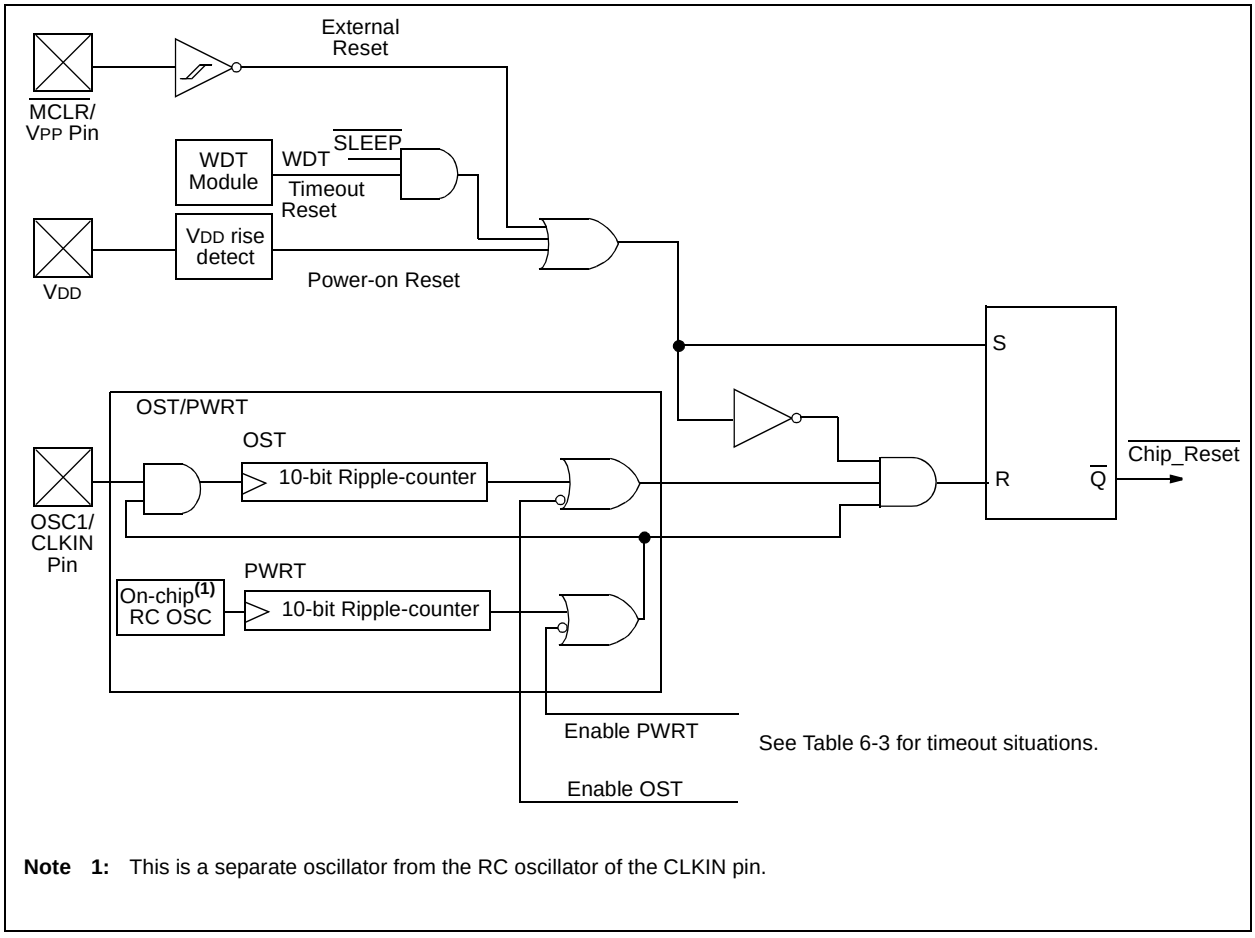
- Power-on Reset (POR)
- $\overline{MCLR}$ Reset during normal operation
- $\overline{MCLR}$ Reset during SLEEP
- WDT Reset (normal operation)
- WDT wake-up (SLEEP)

Some registers are not affected in any RESET condition; their status is unknown on POR and unchanged in any other RESET. Most other registers are reset to a "RESET state" on Power-on Reset, on $\overline{MCLR}$ or WDT Reset and on $\overline{MCLR}$ Reset during SLEEP. They are not affected by a WDT wake-up, since this is viewed as the resumption of normal operation. $\overline{TO}$ and $\overline{PD}$ bits are set or cleared differently in different RESET situations as indicated in Table 6-4. These bits are used in software to determine the nature of the RESET. See Table 6-6 for a full description of RESET states of all registers.

A simplified block diagram of the on-chip RESET circuit is shown in Figure 6-6.

The $\overline{MCLR}$ Reset path has a noise filter to detect and ignore small pulses. See Table 10-3 for pulse width specification.

FIGURE 6-6: SIMPLIFIED BLOCK DIAGRAM OF ON-CHIP RESET CIRCUIT



Note 1: This is a separate oscillator from the RC oscillator of the CLKIN pin.

FIGURE 6-9: TIMEOUT SEQUENCE ON POWER-UP (MCLR TIED TO VDD): CASE 3

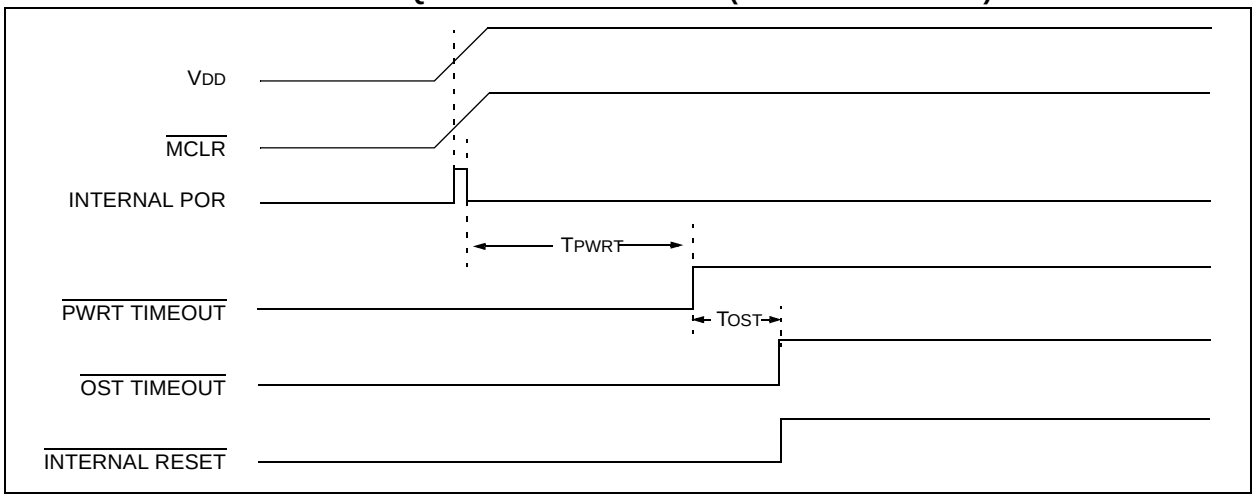
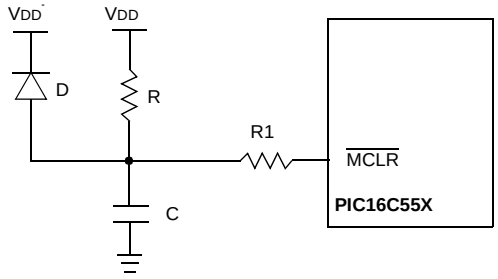


FIGURE 6-10: EXTERNAL POWER-ON RESET CIRCUIT (FOR SLOW VDD POWER-UP)



Note 1: External Power-on Reset circuit is required only if VDD power-up slope is too slow. The diode D helps discharge the capacitor quickly when VDD powers down.

2: < 40 kΩ is recommended to make sure that voltage drop across R does not violate the device's electrical specification.

3: R1 = 100Ω to 1 kΩ will limit any current flowing into MCLR from external capacitor C in the event of MCLR/VPP pin breakdown due to Electrostatic Discharge (ESD) or Electrical Overstress (EOS).

6.9 Code Protection

If the code protection bit(s) have not been programmed, the on-chip program memory can be read out for verification purposes.

Note:	Microchip does not recommend code protecting windowed devices.

6.10 ID Locations

Four memory locations (2000h-2003h) are designated as ID locations where the user can store checksum or other code-identification numbers. These locations are not accessible during normal execution but are readable and writable during program/verify.

6.11 In-Circuit Serial Programming™

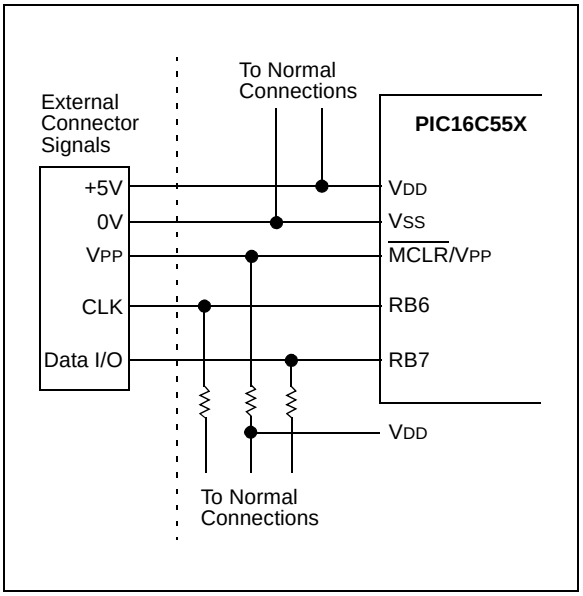
The PIC16C55X microcontrollers can be serially programmed while in the end application circuit. This is simply done with two lines for clock and data, and three other lines for power, ground, and the programming voltage. This allows customers to manufacture boards with unprogrammed devices, and then program the microcontroller just before shipping the product. This also allows the most recent firmware or a custom firmware to be programmed.

The device is placed into a Program/Verify mode by holding the RB6 and RB7 pins low while raising the $\overline{MCLR}$ (V_{PP}) pin from V_{IL} to V_{IHH} (see programming specification). RB6 becomes the programming clock and RB7 becomes the programming data. Both RB6 and RB7 are Schmitt Trigger inputs in this mode.

After RESET, to place the device into Programming/ Verify mode, the program counter (PC) is at location 00h. A 6-bit command is then supplied to the device. Depending on the command, 14 bits of program data are then supplied to or from the device, depending if the command was a load or a read. For complete details of serial programming, please refer to the PIC16C6X/7X Programming Specifications (Literature #DS30228).

A typical in-circuit serial programming connection is shown in Figure 6-15.

FIGURE 6-15: TYPICAL IN-CIRCUIT SERIAL PROGRAMMING CONNECTION



7.3.1 SWITCHING PRESCALER ASSIGNMENT

The prescaler assignment is fully under software control (i.e., it can be changed “on the fly” during program execution). To avoid an unintended device RESET, the following instruction sequence (Example 7-1) must be executed when changing the prescaler assignment from Timer0 to WDT. Lines 5-7 are required only if the desired postscaler rate is 1:1 (PS<2:0> = 000) or 1:2 (PS<2:0> = 001).

EXAMPLE 7-1: CHANGING PRESCALER (TIMER0→WDT)

```
BCF    STATUS, RP0 ;Skip if already in
                   ;Bank 0 CLRWDT Clear WDT
CLRF   TMR0        ;Clear TMR0 & Prescaler
BSF    STATUS, RP0 ;Bank 1
MOVLW  '00101111'b ;These 3 lines (5, 6, 7)
MOVWF  OPTION      ;Are required only if
                   ;Desired PS<2:0> are
                   ;CLRWDT 000 or 001
MOVLW  '00101xxx'b ;Set Postscaler to
MOVWF  OPTION      ;Desired WDT rate
BCF    STATUS, RP0 ;Return to Bank 0
```

To change prescaler from the WDT to the TMR0 module use the sequence shown in Example 7-2. This precaution must be taken even if the WDT is disabled.

EXAMPLE 7-2: CHANGING PRESCALER (WDT→TIMER0)

```
CLRWDT                ;Clear WDT and
                      ;prescaler
BSF     STATUS, RP0
MOVLW   b'xxxx0xxx'   ;Select TMR0, new
                      ;prescale value and
                      ;clock source
MOVWF   OPTION
BCF     STATUS, RP0
```

TABLE 7-1: REGISTERS ASSOCIATED WITH TIMER0

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	Value on POR	Value on All Other RESETS
01h	TMR0	Timer0 module's register								xxxx xxxx	uuuu uuuu
0Bh/8Bh	INTCON	GIE	Reserved	T0IE	INTE	RBIE	T0IF	INTF	RBIF	0000 000x	0000 000x
81h	OPTION	$\overline{\text{RBPU}}$	INTEDG	T0CS	T0SE	PSA	PS2	PS1	PS0	1111 1111	1111 1111
85h	TRISA	—	—	—	TRISA4	TRISA3	TRISA2	TRISA1	TRISA0	---1 1111	---1 1111

Legend: — = Unimplemented locations, read as ‘0’,
Note 1: Shaded bits are not used by TMR0 module.

DECFSZ **Decrement f, Skip if 0**

Syntax: [*label*] DECFSZ f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (f) - 1 → (dest); skip if result = 0

Status Affected: None

Encoding:

00	1011	dfff	ffff

Description: The contents of register 'f' are decremented. If 'd' is 0 the result is placed in the W register. If 'd' is 1 the result is placed back in register 'f'.
If the result is 0, the next instruction, which is already fetched, is discarded. A NOP is executed instead making it a two-cycle instruction.

Words: 1

Cycles: 1(2)

Example

```
HERE     DECFSZ   CNT, 1
         GOTO     LOOP
CONTINUE •
         •
         •
```

Before Instruction
PC = address HERE
After Instruction
CNT = CNT - 1
if CNT = 0,
PC = address CONTINUE
if CNT ≠ 0,
PC = address HERE+1

GOTO **Unconditional Branch**

Syntax: [*label*] GOTO k

Operands: $0 \le k \le 2047$

Operation: k → PC<10:0>
PCLATH<4:3> → PC<12:11>

Status Affected: None

Encoding:

10	1kkk	kkkk	kkkk

Description: GOTO is an unconditional branch. The eleven bit immediate value is loaded into PC bits <10:0>. The upper bits of PC are loaded from PCLATH<4:3>. GOTO is a two-cycle instruction.

Words: 1

Cycles: 2

Example

```
GOTO THERE
```

After Instruction
PC = Address THERE

INCF **Increment f**

Syntax: [*label*] INCF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (f) + 1 → (dest)

Status Affected: Z

Encoding:

00	1010	dfff	ffff

Description: The contents of register 'f' are incremented. If 'd' is 0 the result is placed in the W register. If 'd' is 1 the result is placed back in register 'f'.

Words: 1

Cycles: 1

Example

```
INCF    CNT,   1
```

Before Instruction
CNT = 0xFF
Z = 0
After Instruction
CNT = 0x00
Z = 1

MOVF **Move f**

Syntax: [*label*] MOVF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (f) → (dest)

Status Affected: Z

Encoding:

00	1000	dfff	ffff

Description: The contents of register f is moved to a destination dependant upon the status of d. If d = 0, destination is W register. If d = 1, the destination is file register f itself. d = 1 is useful to test a file register since status flag Z is affected.

Words: 1

Cycles: 1

Example
```
MOVF    FSR,   0
```
After Instruction
W = value in FSR register
Z = 1

MOVWF **Move W to f**

Syntax: [*label*] MOVWF f

Operands: $0 \le f \le 127$

Operation: (W) → (f)

Status Affected: None

Encoding:

00	0000	1fff	ffff

Description: Move data from W register to register 'f'.

Words: 1

Cycles: 1

Example
```
MOVWF   OPTION
```
Before Instruction
OPTION = 0xFF
W = 0x4F
After Instruction
OPTION = 0x4F
W = 0x4F

NOP **No Operation**

Syntax: [*label*] NOP

Operands: None

Operation: No operation

Status Affected: None

Encoding:

00	0000	0xx0	0000

Description: No operation.

Words: 1

Cycles: 1

Example
```
NOP
```

OPTION **Load Option Register**

Syntax: [*label*] OPTION

Operands: None

Operation: (W) → OPTION

Status Affected: None

Encoding:

00	0000	0110	0010

Description: The contents of the W register are loaded in the OPTION register. This instruction is supported for code compatibility with PIC16C5X products. Since OPTION is a readable/writable register, the user can directly address it.

Words: 1

Cycles: 1

Example

To maintain upward compatibility with future PIC MCU products, do not use this instruction.

XORLW **Exclusive OR Literal with W**

Syntax: [*label*] XORLW k

Operands: $0 \le k \le 255$

Operation: (W) .XOR. k → (W)

Status Affected: Z

Encoding:

11	1010	kkkk	kkkk

Description: The contents of the W register are XOR'ed with the eight bit literal 'k'. The result is placed in the W register.

Words: 1

Cycles: 1

Example:

```
XORLW   0xAF
```

Before Instruction

W = 0xB5

After Instruction

W = 0x1A

XORWF **Exclusive OR W with f**

Syntax: [*label*] XORWF f,d

Operands: $0 \le f \le 127$
$d \in [0,1]$

Operation: (W) .XOR. (f) → (dest)

Status Affected: Z

Encoding:

00	0110	dfff	ffff

Description: Exclusive OR the contents of the W register with register 'f'. If 'd' is 0 the result is stored in the W register. If 'd' is 1 the result is stored back in register 'f'.

Words: 1

Cycles: 1

Example

```
XORWF   REG     1
```

Before Instruction

REG = 0xAF
W = 0xB5

After Instruction

REG = 0x1A
W = 0xB5

9.4 MPLINK Object Linker/ MPLIB Object Librarian

The MPLINK object linker combines relocatable objects created by the MPASM assembler and the MPLAB C17 and MPLAB C18 C compilers. It can also link relocatable objects from pre-compiled libraries, using directives from a linker script.

The MPLIB object librarian is a librarian for pre-compiled code to be used with the MPLINK object linker. When a routine from a library is called from another source file, only the modules that contain that routine will be linked in with the application. This allows large libraries to be used efficiently in many different applications. The MPLIB object librarian manages the creation and modification of library files.

The MPLINK object linker features include:

- Integration with MPASM assembler and MPLAB C17 and MPLAB C18 C compilers.
- Allows all memory areas to be defined as sections to provide link-time flexibility.

The MPLIB object librarian features include:

- Easier linking because single libraries can be included instead of many smaller files.
- Helps keep code maintainable by grouping related modules together.
- Allows libraries to be created and modules to be added, listed, replaced, deleted or extracted.

9.5 MPLAB SIM Software Simulator

The MPLAB SIM software simulator allows code development in a PC-hosted environment by simulating the PIC series microcontrollers on an instruction level. On any given instruction, the data areas can be examined or modified and stimuli can be applied from a file, or user-defined key press, to any of the pins. The execution can be performed in single step, execute until break, or Trace mode.

The MPLAB SIM simulator fully supports symbolic debugging using the MPLAB C17 and the MPLAB C18 C compilers and the MPASM assembler. The software simulator offers the flexibility to develop and debug code outside of the laboratory environment, making it an excellent multi-project software development tool.

9.6 MPLAB ICE High Performance Universal In-Circuit Emulator with MPLAB IDE

The MPLAB ICE universal in-circuit emulator is intended to provide the product development engineer with a complete microcontroller design tool set for PIC microcontrollers (MCUs). Software control of the MPLAB ICE in-circuit emulator is provided by the MPLAB Integrated Development Environment (IDE), which allows editing, building, downloading and source debugging from a single environment.

The MPLAB ICE 2000 is a full-featured emulator system with enhanced trace, trigger and data monitoring features. Interchangeable processor modules allow the system to be easily re configured for emulation of different processors. The universal architecture of the MPLAB ICE in-circuit emulator allows expansion to support new PIC microcontrollers.

The MPLAB ICE in-circuit emulator system has been designed as a real-time emulation system, with advanced features that are generally found on more expensive development tools. The PC platform and Microsoft® Windows environment were chosen to best make these features available to you, the end user.

9.7 ICEPIC In-Circuit Emulator

The ICEPIC low cost, in-circuit emulator is a solution for the Microchip Technology PIC16C5X, PIC16C6X, PIC16C7X and PIC16CXXX families of 8-bit One-Time-Programmable (OTP) microcontrollers. The modular system can support different subsets of PIC16C5X or PIC16CXXX products through the use of interchangeable personality modules, or daughter boards. The emulator is capable of emulating without target application circuitry being present.

TABLE 10-2: CLKOUT AND I/O TIMING REQUIREMENTS

Parameter #	Sym	Characteristic	Min	Typ†	Max	Units
10*	TosH2ckL	OSC1↑ to CLKOUT↓ (1)	— —	75 —	200 400	ns ns
11*	TosH2ckH	OSC1↑ to CLKOUT↑ (1)	— —	75 —	200 400	ns ns
12*	TckR	CLKOUT rise time(1)	— —	35 —	100 200	ns ns
13*	TckF	CLKOUT fall time(1)	— —	35 —	100 200	ns ns
14*	TckL2ioV	CLKOUT ↓ to Port out valid(1)	—	—	20	ns
15*	TioV2ckH	Port in valid before CLKOUT ↑ (1)	Tosc +200 ns Tosc +400 ns	— —	— —	ns ns
16*	TckH2ioI	Port in hold after CLKOUT ↑ (1)	0	—	—	ns
17*	TosH2ioV	OSC1↑ (Q1 cycle) to Port out valid	— —	50	150 300	ns ns
18*	TosH2ioI	OSC1↑ (Q2 cycle) to Port input invalid (I/O in hold time)	100 200	— —	— —	ns ns
19*	TioV2osH	Port input valid to OSC1↑ (I/O in setup time)	0	—	—	ns
20*	TioR	Port output rise time	— —	10 —	40 80	ns ns
21*	TioF	Port output fall time	— —	10 —	40 80	ns ns
22*	Tinp	RB0/INT pin high or low time	25 40	— —	— —	ns ns
23*	Trbp	RB<7:4> change interrupt high or low time	Tcy	—	—	ns

* These parameters are characterized but not tested.

† Data in “Typ” column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Measurements are taken in RC mode where CLKOUT output is 4 x TOSC.

FIGURE 10-9: TIMER0 CLOCK TIMING

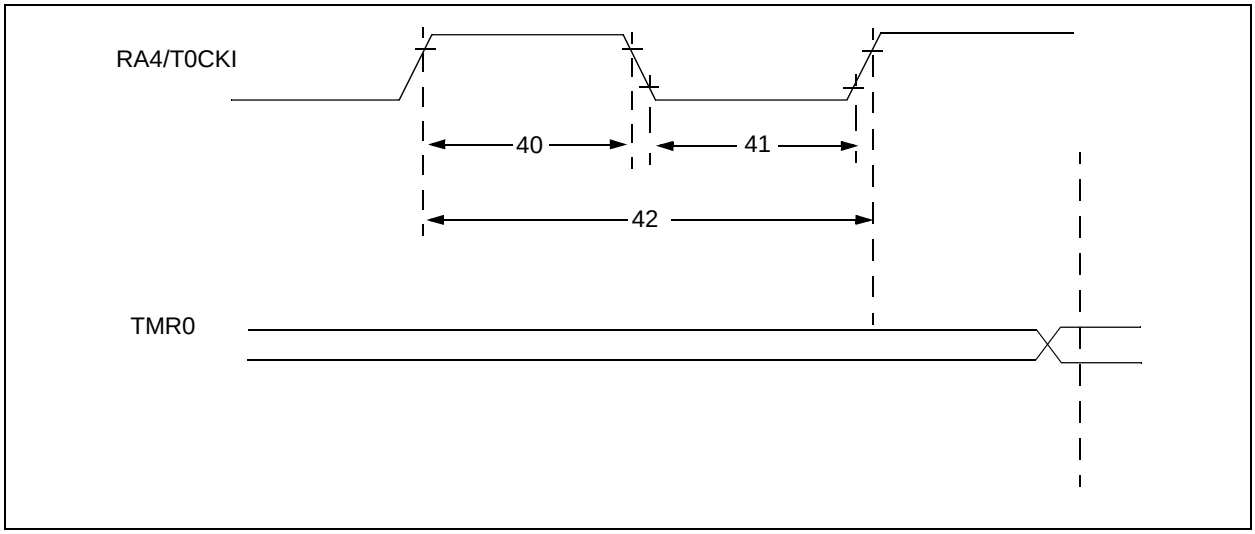


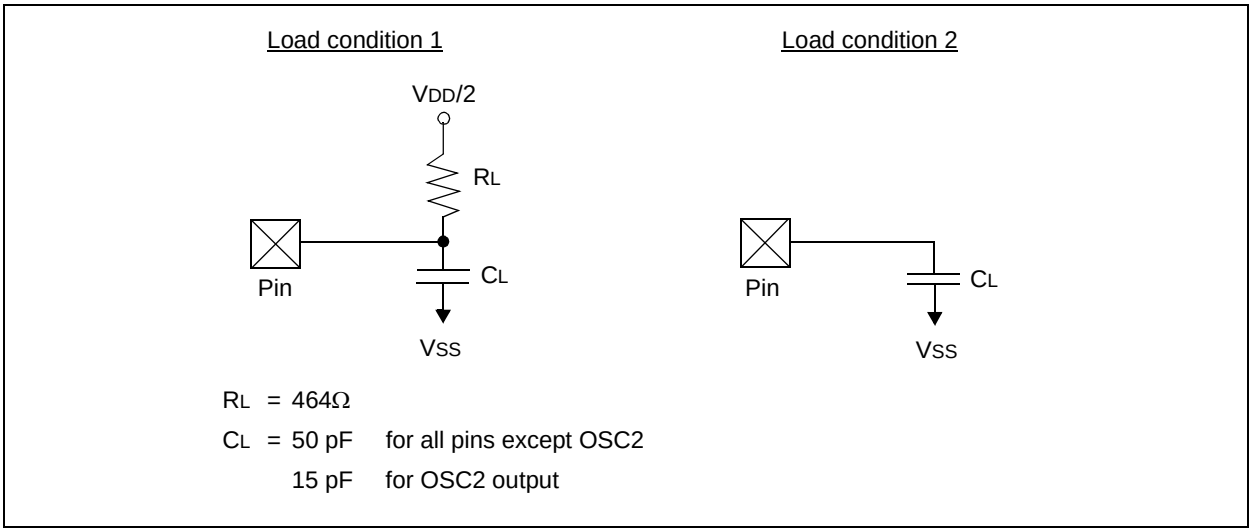
TABLE 10-4: TIMER0 CLOCK REQUIREMENTS

Param No.	Sym	Characteristic		Min	Typ†	Max	Units	Conditions
40	Tt0H	T0CKI High Pulse Width	No Prescaler	0.5 TCY + 20*	—	—	ns	
			With Prescaler	10*	—	—	ns	
41	Tt0L	T0CKI Low Pulse Width	No Prescaler	0.5 TCY + 20*	—	—	ns	
			With Prescaler	10*	—	—	ns	
42	Tt0P	T0CKI Period		$\frac{T_{CY} + 40}{N}$*	—	—	ns	N = prescale value (1, 2, 4, ..., 256)

* These parameters are characterized but not tested.

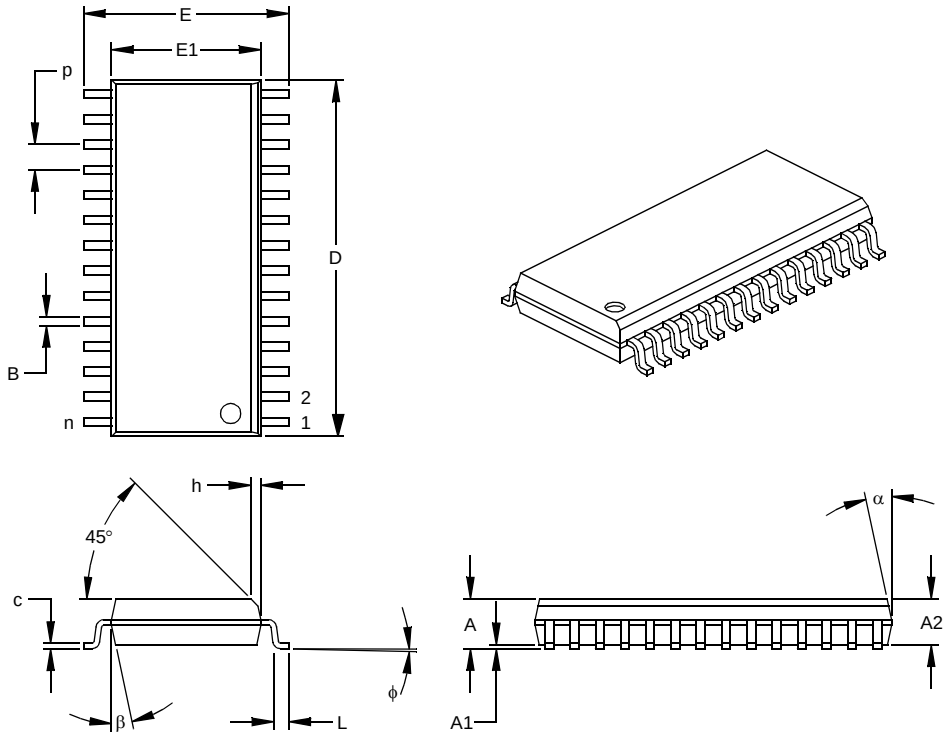
† Data in "Typ" column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

FIGURE 10-10: LOAD CONDITIONS



28-Lead Plastic Small Outline (SO) – Wide, 300 mil (SOIC)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



Units		INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		28			28	
Pitch	p		.050			1.27	
Overall Height	A	.093	.099	.104	2.36	2.50	2.64
Molded Package Thickness	A2	.088	.091	.094	2.24	2.31	2.39
Standoff §	A1	.004	.008	.012	0.10	0.20	0.30
Overall Width	E	.394	.407	.420	10.01	10.34	10.67
Molded Package Width	E1	.288	.295	.299	7.32	7.49	7.59
Overall Length	D	.695	.704	.712	17.65	17.87	18.08
Chamfer Distance	h	.010	.020	.029	0.25	0.50	0.74
Foot Length	L	.016	.033	.050	0.41	0.84	1.27
Foot Angle Top	ϕ	0	4	8	0	4	8
Lead Thickness	c	.009	.011	.013	0.23	0.28	0.33
Lead Width	B	.014	.017	.020	0.36	0.42	0.51
Mold Draft Angle Top	α	0	12	15	0	12	15
Mold Draft Angle Bottom	β	0	12	15	0	12	15

* Controlling Parameter
§ Significant Characteristic

Notes:
Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010” (0.254mm) per side.
JEDEC Equivalent: MS-013
Drawing No. C04-052

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